

IN THE SPECIFICATION:

Please amend paragraph number [0029] as follows:

[0029] FIG. 32 is a side cross-sectional view of a prior art temporary package with two solder balls of a die, one ~~undersized~~, under-sized, disposed thereagainst.

Please amend paragraph number [0030] as follows:

[0030] FIGS. 1-9 illustrate side cross-sectional views of a method of forming a single interconnection of the present invention, although typically hundreds, if not thousands, of such interconnections may be simultaneously fabricated on a single substrate. It should be understood that the figures presented in conjunction with this description are not meant to be illustrations of actual cross-sectional views of any particular portion of an actual semiconductor device, but are merely idealized representations, ~~which~~ that are employed to more clearly and fully depict the process of the invention than would otherwise be possible. It should also be understood that the figures herein are not meant to be to scale nor otherwise in specific proportion, nor should they be so taken.